Amendments to the Claims:

This listing of claims will replace all prior versions, and listing, of claims in the present application:

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Listing of Claims:

1. (withdrawn) A unitary retaining ring for use in a Chemical Mechanical Polishing (CMP) apparatus comprising:

a pad engaging surface which is designed to be flat and planar when the retaining ring is mounted to a carrier of the CMP apparatus;

a carrier engaging surface located opposite the pad engaging surface; and,

a plurality of mounting features located along the carrier engaging surface, the mounting features being installed to cause localized compressive stress in the retaining ring when in a de-mounted state;

whereby upon mounting to a carrier under specified torque or force conditions, tensile stresses are applied to the retaining ring in the vicinity of the localized compressive stress resulting in a flat and planar mounted pad engaging surface.

2. (withdrawn) The unitary retaining ring of claim 1 wherein the plurality of mounting features include reinforcing members mounted within holes on the carrier engaging surface whereby the localized compressive stress is caused by the fit between the reinforcing member and the hole.

3. (withdrawn) The unitary retaining ring of claim 2 further comprising channels being formed in the pad engaging surface extending from an inner surface to an outer surface of the ring.